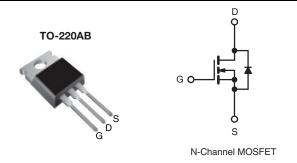


Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	400 V				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V 1.8				
Q _g (Max.) (nC)	20				
Q _{gs} (nC)	3.3				
Q _{gd} (nC)	11				
Configuration	Single				



FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

This datasheet provides information about parts that are RoHS-compliant and/or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information/tables in this datasheet for details.

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF720PbF
	SiHF720-E3
SnPb	IRF720
	SiHF720

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	400	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current	V_{GS} at 10 V $T_C = 25 ^{\circ}\text{C}$		3.3	
Continuous Drain Current	$T_C = 100 ^{\circ}$ C	I _D	2.1	Α
Pulsed Drain Current ^a	I _{DM}	13		
Linear Derating Factor		0.40	W/°C	
Single Pulse Avalanche Energy b	E _{AS}	190	mJ	
Repetitive Avalanche Current ^a	I _{AR}	3.3	Α	
Repetitive Avalanche Energy ^a	E _{AR}	5.0	mJ	
Maximum Power Dissipation	P _D	50	W	
Peak Diode Recovery dV/dt ^c	dV/dt	4.0	V/ns	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	1 00	
Soldering Recommendations (Peak Temperature) d		300	°C	
Mounting Torque	0.00 - 110		10	lbf ⋅ in
	6-32 or M3 screw		1.1	N · m

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD}=50$ V, starting $T_J=25$ °C, L=30 mH, $R_g=25$ Ω , $I_{AS}=3.3$ A (see fig. 12). c. $I_{SD}\leq 3.3$ A, $dI/dt\leq 65$ A/µs, $V_{DD}\leq V_{DS}$, $T_J\leq 150$ °C.

- d. 1.6 mm from case.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	2.5		

PARAMETER	SYMBOL	TEST (MIN.	TYP.	MAX.	UNIT	
Static					<u> </u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference t	Reference to 25 °C, I _D = 1 mA		0.51	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_0$	$V_{DS} = V_{GS}, I_D = 250 \mu A$		-	4.0	V
Gate-Source Leakage	I _{GSS}	Vo	$a_{SS} = \pm 20$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}		00 V, V _{GS} = 0 V V _{GS} = 0 V, T _J = 125 °C	-	-	25 250	μΑ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V		-	-	1.8	Ω
Forward Transconductance	9 _{fs}) V, I _D = 2.0 A ^b	1.7	-	-	S
Dynamic	013		, , ,		ļ		
Input Capacitance	C _{iss}	V	_{GS} = 0 V,	-	410	-	
Output Capacitance	C _{oss}		$_{OS} = 0 \text{ V},$ $_{OS} = 25 \text{ V},$	-	120	-	pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 N	MHz, see fig. 5	-	47	-	
Total Gate Charge	Qq		In = 3.3 A.	-	-	20	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 320 \text{ V},$	-	-	3.3	
Gate-Drain Charge	Q _{gd}		see fig. 6 and 13 b	-	-	11	
Turn-On Delay Time	t _{d(on)}			-	10	-	
Rise Time	t _r	V 200 V I 2.2 A		-	14	-	ns
Turn-Off Delay Time	t _{d(off)}		$V_{DD} = 200 \text{ V}, I_D = 3.3 \text{ A}$ $R_g = 18 \Omega, R_D = 56 \Omega, \text{ see fig. } 10^{\text{ b}}$		30	-	
Fall Time	t _f	g,,		-	13	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	ml I
Internal Source Inductance	L _S			-	7.5	-	nH
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		_	-	3.3	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	13	A
Body Diode Voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 3.3 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	1.6	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 3.3 A, dl/dt = 100 A/μs b		-	270	600	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	1.4	3.0	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-	on time is negligible (turn	ı-on is doı	minated b	by L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

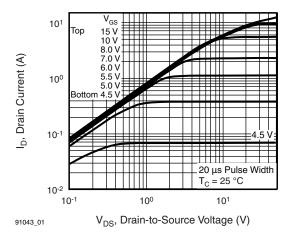


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

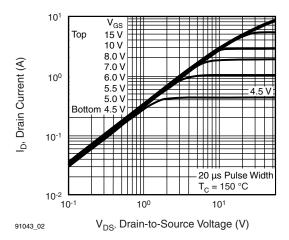


Fig. 2 - Typical Output Characteristics, $T_C = 150 \, ^{\circ}\text{C}$

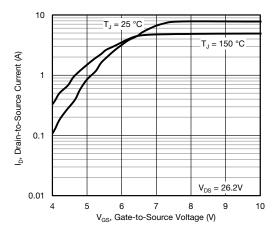


Fig. 3 - Typical Transfer Characteristics

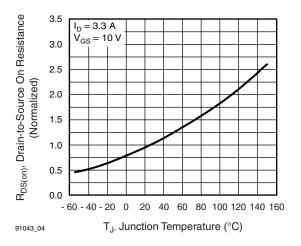


Fig. 4 - Normalized On-Resistance vs. Temperature

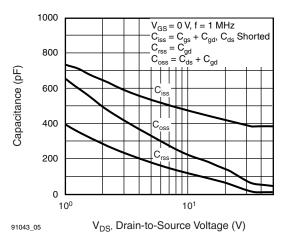


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

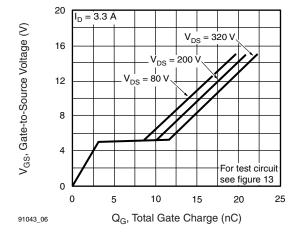


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



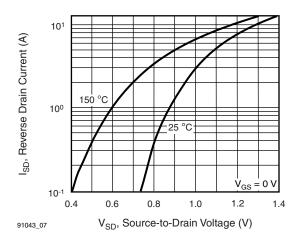


Fig. 7 - Typical Source-Drain Diode Forward Voltage

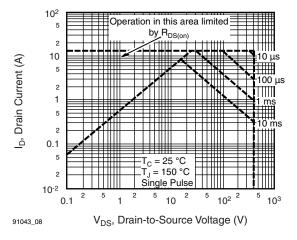


Fig. 8 - Maximum Safe Operating Area

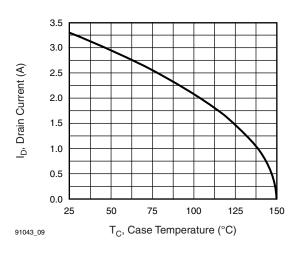


Fig. 9 - Maximum Drain Current vs. Case Temperature

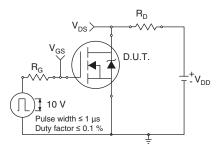


Fig. 10a - Switching Time Test Circuit

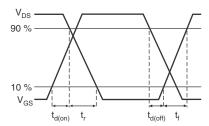


Fig. 10b - Switching Time Waveforms

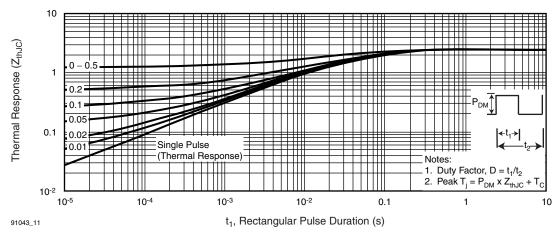


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



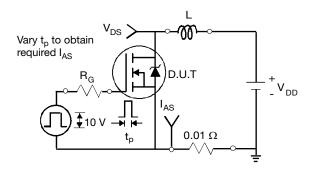


Fig. 12a - Unclamped Inductive Test Circuit

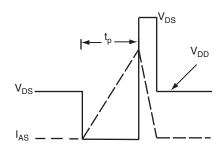


Fig. 12b - Unclamped Inductive Waveforms

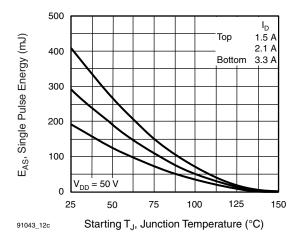


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

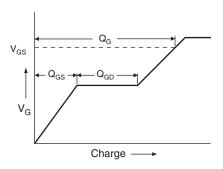


Fig. 13a - Basic Gate Charge Waveform

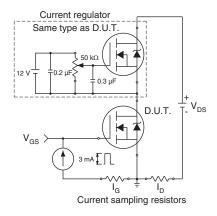
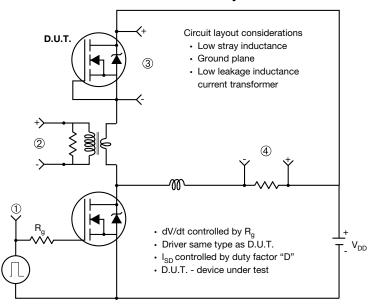


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



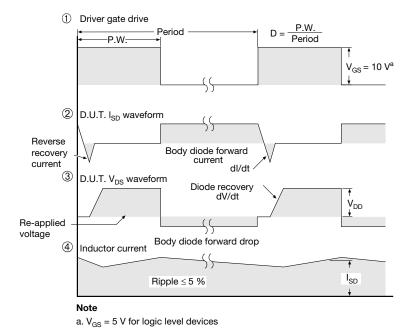


Fig. 14 - For N-Channel

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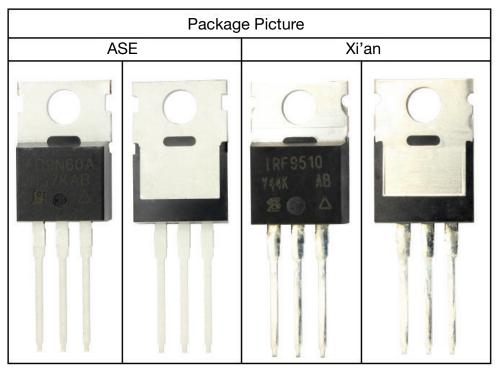
TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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